MATERIAL DECLARATION SHEET

Material Number	ESD Suppressing Device CDDFN2-T3.3B		
Product Line	Semiconductor Products		
Compliance Date	**2013/8/2**		
RoHS Compliant	**Yes**	MSL	**3**

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.0357	Silicon	7440-21-3	100.00%	3.855%	3.855%
2	Lead frame	Copper Alloy (NiPdAu)	0.4182	Copper	7440-50-8	95.31%	45.152%	47.377%
			0.013	Nickel	7440-02-0	2.97%	1.404%	
			0.0028	Silicon	7440-21-3	0.64%	0.302%	
			0.0007	Magnesium	7439-95-4	0.15%	0.076%	
		Ni plating	0.0037	Nickel	7440-02-0	0.85%	0.400%	
		Pd plating	0.0003	Palladium	7440-57-3	0.06%	0.032%	
		Au plating	0.0001	Gold	7440-57-5	0.02%	0.011%	
3	Epoxy	Polymer	0.006	Silver	7440-22-4	80.50%	0.648%	0.826%
			0.001	Carbocyclic Acrylates	proprietary	10.00%	0.108%	
			0.0002	Bismaleimide resin	proprietary	3.00%	0.022%	
			0.0002	2-preponoic acid, 2-methyl	68586-19-6	3.00%	0.022%	
			0.0002	Additive, not to declare	proprietary	3.00%	0.022%	
			0.00004	Dicumyl peroxide	80-43-3	0.50%	0.004%	
			0.0049	Gold	7440-57-5	99.99%	0.529%	

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			0.0001	Other, not to declare	/	0.01%	0.011%	
5	Mold Compound	Polymer	0.412	Silica Fused	60676-86-0	93.70%	44.486%	47.402%
			0.013	Epoxy Resin	Proprietary	3.00%	1.404%	
			0.013	Phenol Resin	Proprietary	3.00%	1.404%	
			0.001	Carbon Black	1333-86-4	0.30%	0.108%	
		Total weight	**0.92614 mg**					

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Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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